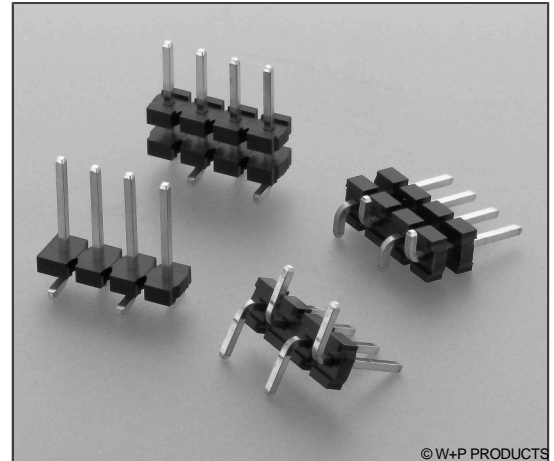


9850 / 9860

SMT-Stiftleisten RM 5,08mm, stehend – Power-Kontakte SMT Pin Headers, 5.08mm Pitch, Vertical – Power Contacts

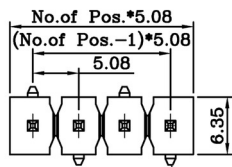
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Vierkantstift 1,14mm, Kupferlegierung <i>1.14mm square pin, copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Lt. Oberflächenoptionen, über Ni <i>Acc. to options (see below), over Ni</i>
RoHS-Ausnahmen 6a-I / 6c <i>RoHS Exemptions 6a-I / 6c</i>	keine <i>none</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ <i>< 20 mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ <i>> 1000 MΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC <i>500 V AC</i>
Nennstrom <i>Current Rating</i>	7,9 A <i>7.9 A</i>
Temperaturbereich <i>Temperature Range</i>	-40 °C ... +105 °C <i>-40 °C ... +105 °C</i>
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>

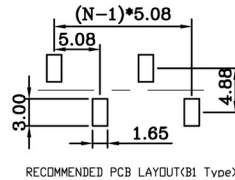
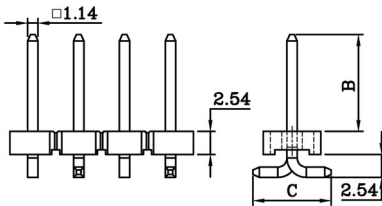


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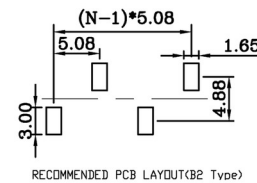
Passende Buchsenleisten:
Compatible Female Headers:
395/396 3950 3960



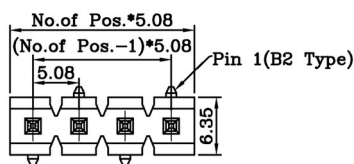
Pin 1 (B1 Type)



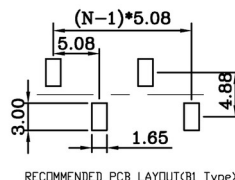
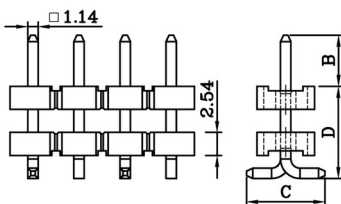
RECOMMENDED PCB LAYOUT (B1 Type)



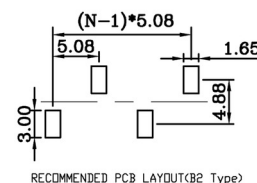
RECOMMENDED PCB LAYOUT (B2 Type)



Pin 1 (B2 Type)



RECOMMENDED PCB LAYOUT (B1 Type)



RECOMMENDED PCB LAYOUT (B2 Type)

Series*	Type*	Contacts*	Rows	Layout*	Plating	Packaging*
9850	10	05	1	1	50	ST
9850 Single Body	10 B=10,72 C=8,64mm (9850)	02-20		1 Layout B1	50 Verzinkt	ST
9860 Dual Body	20 B=12,24 C=8,38mm (9850)			2 Layout B2	Tin plated	PPST
	30 B=5,64 C=8,64 D=10,16mm (9860)					PPTR (Option)

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** - please replace by your specifications.

Lieferformen / Packaging Options:

ST In Stangen / In tubes
PPST In Stangen mit Pick&Place-Pads / In tubes with Pick&Place-Pads
PPTR (Option) Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

Informationen zum Reflow-Lötverfahren Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	217 °C
Duration above T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

